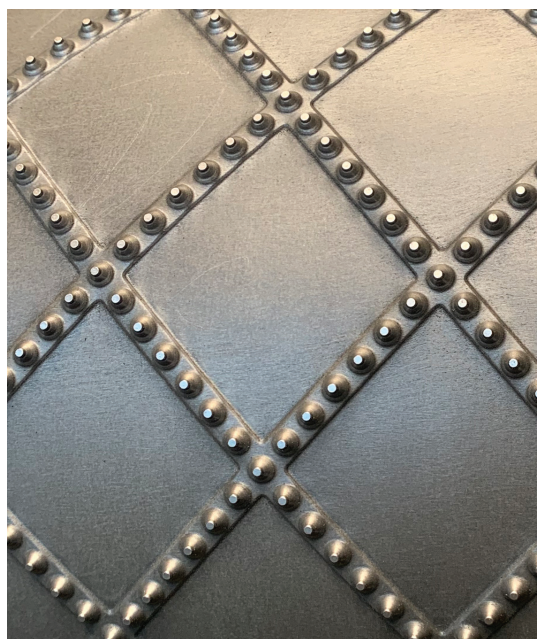


“Large Diamond” Roll Pattern

Pin spacing, center to center: Open Area:	7.3 mm 50 x 50 mm
Pin OD:	1.7 mm
Pin height:	2.5 mm
Pin area:	2.3 sqmm
Number of pins per sqcm:	0.58
Overall bonded area:	1.3 %
Typical applications:	<p>Medium to heavy weight composites; absorbent materials for environmental applications, filtration.</p> <p>The high pin height and the increased depth of the open areas, allows for heavy and bulky composite lamination of up to 350g/sqm.</p>
Limitations:	Due to the low number of bonding points, the strength of the inter-ply adhesion is limited.



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